



# STV300NH02L

N-channel 24V - 0.8mΩ - 280A - PowerSO-10  
STripFET™ Power MOSFET

## Features

Type	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STV300NH02L	24V	0.001Ω	280A

- R<sub>DS(on)</sub>\*Q<sub>g</sub> industry's benchmark
- Conduction losses reduced
- Low profile, very low parasitic inductance
- Switching losses reduced

## Applications

- Switching applications
  - OR-ing
- Specially designed and optimized for high efficiency DC/DC converters.

## Description

This product utilizes the latest advanced design rules of ST's proprietary STripFET™ technology. This is suitable for high current OR-ing application.

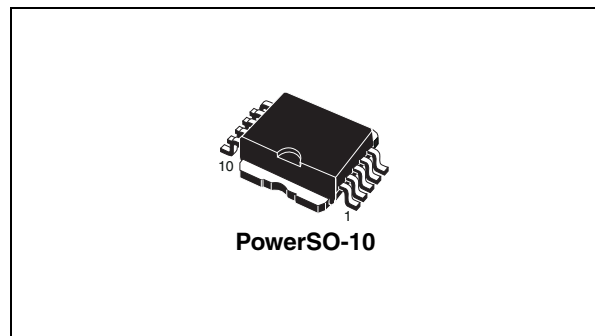


Figure 1. Internal schematic diagram

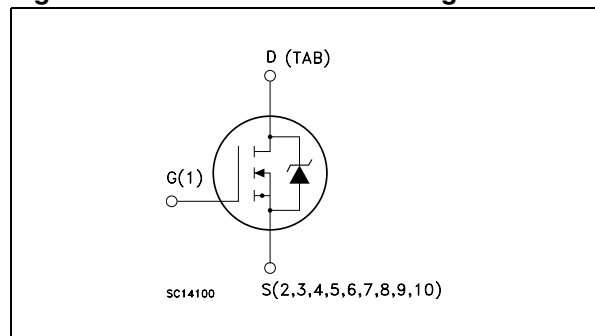


Figure 2. Connection diagram (top view)

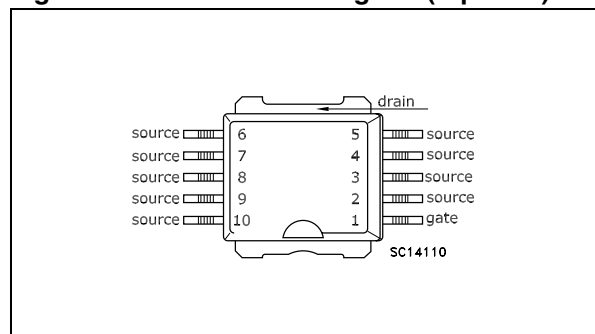


Table 1. Device summary

Order code	Marking	Package	Packaging
STV300NH02L	300NH02L	PowerSO-10	Tape & reel

## Content

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage ( $v_{gs} = 0$ )	24	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	280	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	200	A
$I_{DM}^{(2)}$	Drain current (pulsed)	1120	A
$P_{TOT}^{(3)}$	Total dissipation at $T_C = 25^\circ\text{C}$	300	W
	Derating factor	2	W/ $^\circ\text{C}$
$E_{AS}^{(4)}$	Single pulse avalanche energy	1.6	J
$T_{stg}$	Storage temperature	-55 to 175	$^\circ\text{C}$
$T_j$	Operating junction temperature		

1. This value is limited by package
2. Pulse with limited by safe operating area
3. This value is rated according to Rthj-c
4. Starting  $T_j = 25^\circ\text{C}$ ,  $I_D = 60\text{A}$ ,  $V_{DD} = 20\text{V}$

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
Rthj-case	Thermal resistance junction-case max	0.5	$^\circ\text{C}/\text{W}$
Rthj-amb	Thermal resistance junction-ambient max	50	$^\circ\text{C}/\text{W}$

## 2 Electrical characteristics

(T<sub>case</sub> = 25°C unless otherwise specified)

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	I <sub>D</sub> = 1mA, V <sub>GS</sub> = 0	24			V
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max rating, V <sub>DS</sub> = Max rating, T <sub>c</sub> = 125°C			1 10	μA μA
I <sub>GSS</sub>	Gate body leakage current (V <sub>DS</sub> = 0)	V <sub>DS</sub> = ± 20V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.5	2	V
R <sub>DS(on)</sub>	Static drain-source on resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 80A		0.8	1	mΩ

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> = 15V, f = 1 MHz, V <sub>GS</sub> = 0		7055		pF
C <sub>OSS</sub>	Output capacitance			3251		pF
C <sub>rSS</sub>	Reverse transfer capacitance			307		pF
Q <sub>g</sub>	Total gate charge	V <sub>DD</sub> = 12V, I <sub>D</sub> = 120A,		109		nC
Q <sub>gs</sub>	Gate-source charge	V <sub>GS</sub> = 10V		30		nC
Q <sub>gd</sub>	Gate-drain charge	(see Figure 15)		26		nC
R <sub>G</sub>	Gate input resistance	V <sub>DS</sub> = 0V, f = 1 MHz, V <sub>GS</sub> = 0		4.4		Ω

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$ $t_r$	Turn-on delay time Rise time	$V_{DD} = 12V, I_D = 60A$ $R_G = 4.7\Omega, V_{GS} = 10V,$ <i>(see Figure 14)</i>		18 275		ns ns
$t_{d(off)}$ $t_f$	Turn-off delay time Fall time	$V_{DD} = 12V, I_D = 60A$ $R_G = 4.7\Omega, V_{GS} = 10V,$ <i>(see Figure 14)</i>		138 94.4		ns ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ $I_{SDM}$	Source-drain current Source-drain current (pulsed)				280 1120	A A
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 120A, V_{GS} = 0$			1.3	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 120A, di/dt = 100A/\mu s$ $V_{DD} = 20V, T_j = 25^\circ C$ <i>(see Figure 19)</i>		63 85 2.7		ns nC A
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 120A, di/dt = 100A/\mu s$ $V_{DD} = 20V, T_j = 150^\circ C$ <i>(see Figure 19)</i>		63 88 2.8		ns nC A

1. Pulsed: Pulse duration = 300  $\mu s$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 3. Safe operating area

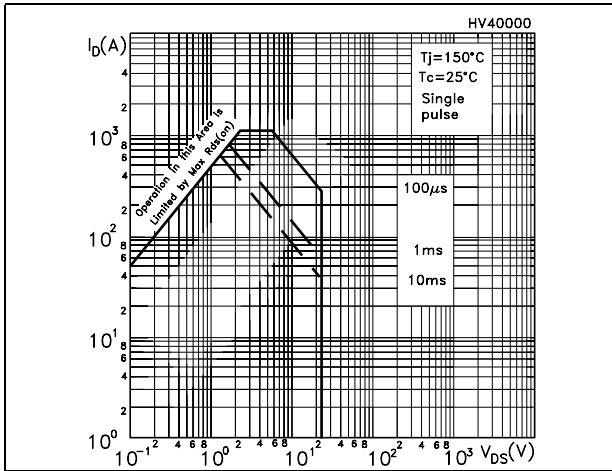


Figure 4. Thermal impedance

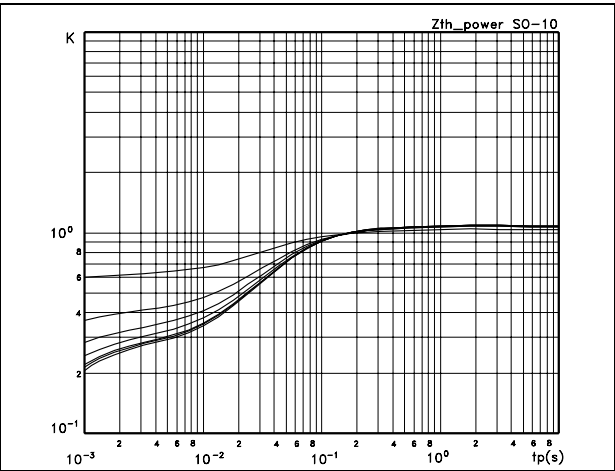


Figure 5. Output characteristics

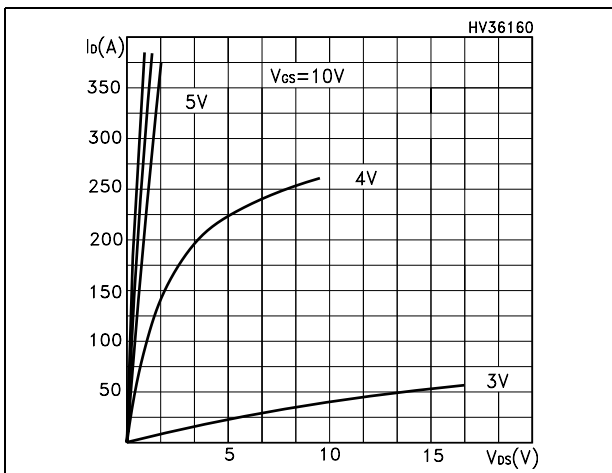


Figure 6. Transfer characteristics

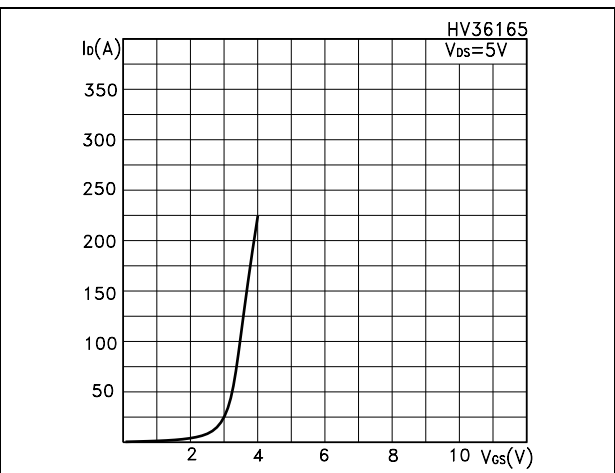


Figure 7. Static drain-source on resistance

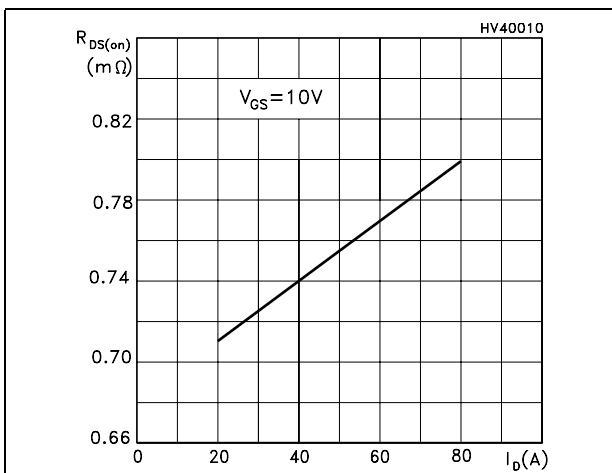


Figure 8. Normalized  $BV_{DSS}$  vs temperature

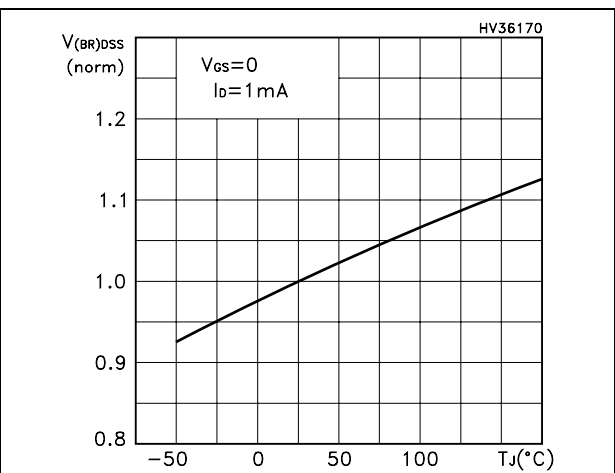


Figure 9. Gate charge vs gate-source voltage Figure 10. Capacitance variations

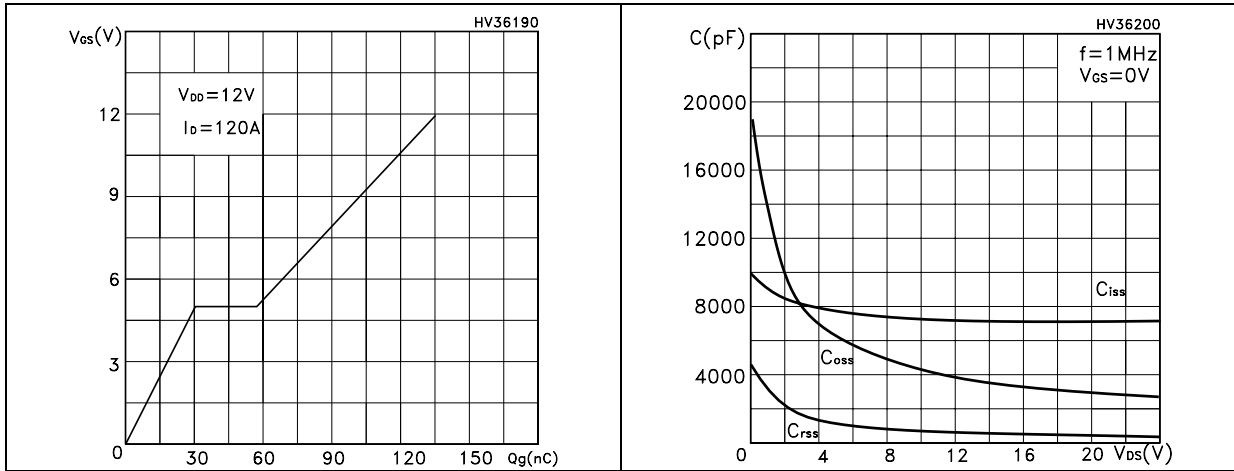


Figure 11. Normalized gate threshold voltage vs temperature Figure 12. Normalized on resistance vs temperature

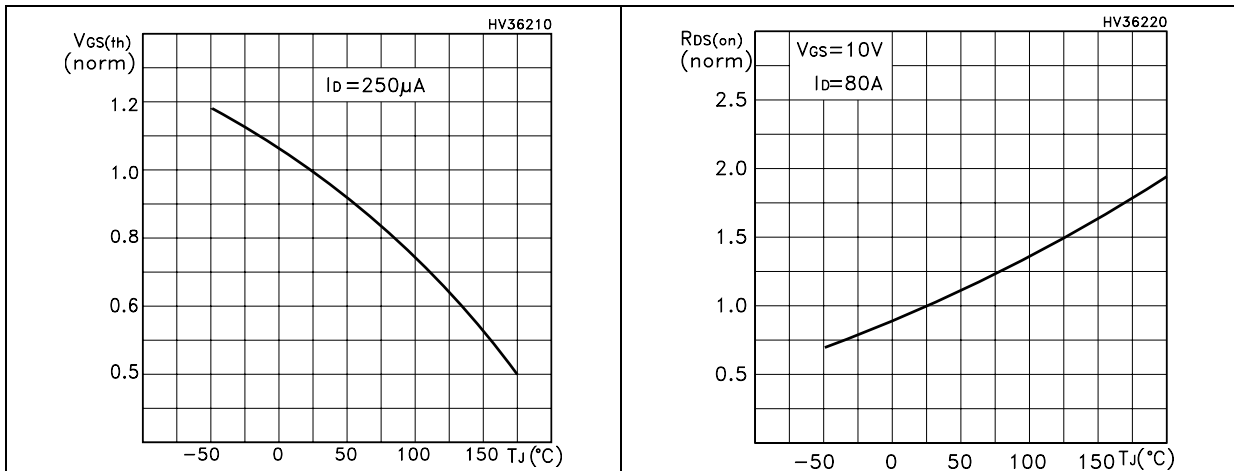
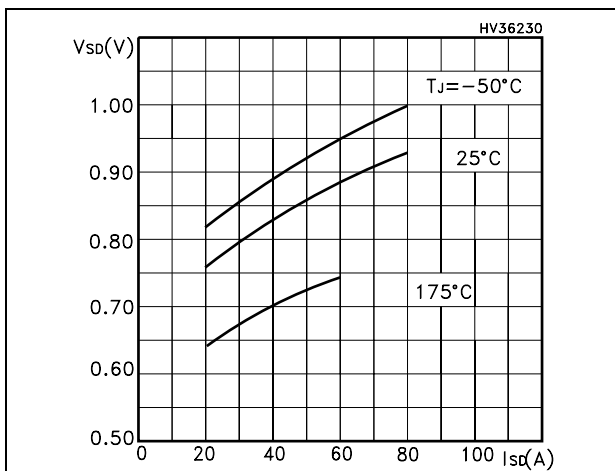
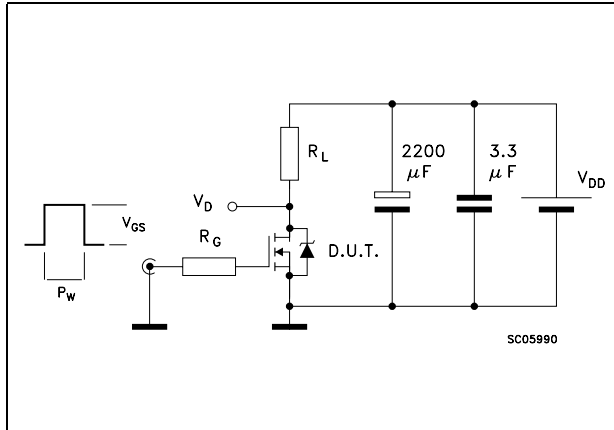


Figure 13. Source-drain diode forward characteristics

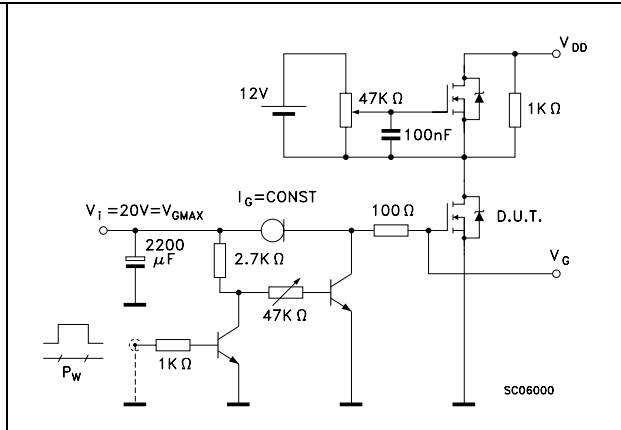


### 3 Test circuits

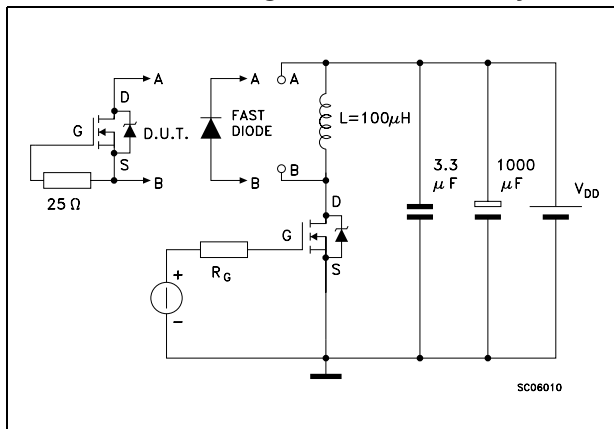
**Figure 14. Switching times test circuit for resistive load**



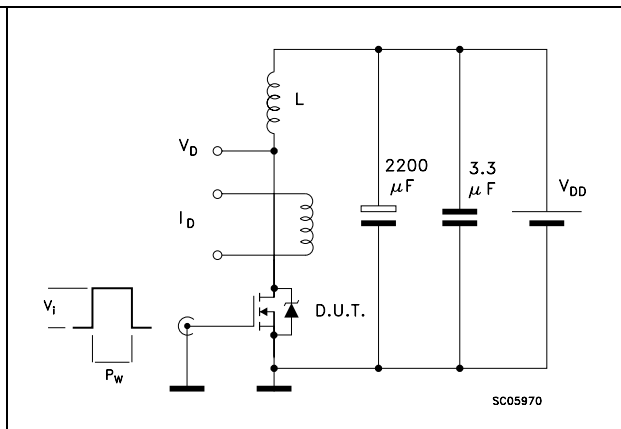
**Figure 15. Gate charge test circuit**



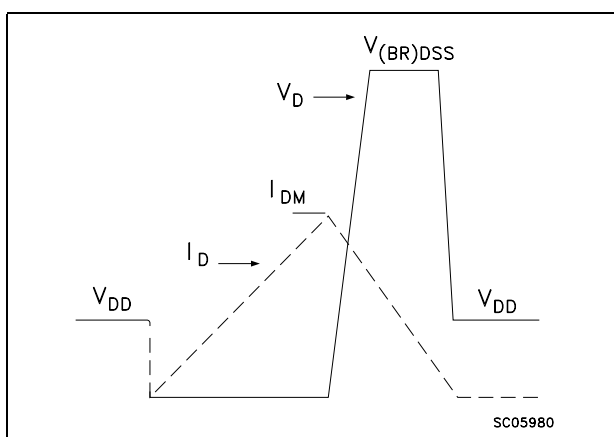
**Figure 16. Test circuit for inductive load switching and diode recovery times**



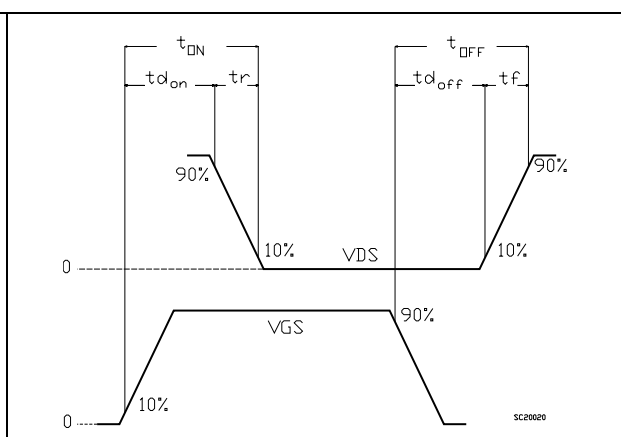
**Figure 17. Unclamped inductive load test circuit**



**Figure 18. Unclamped inductive waveform**



**Figure 19. Switching time waveform**



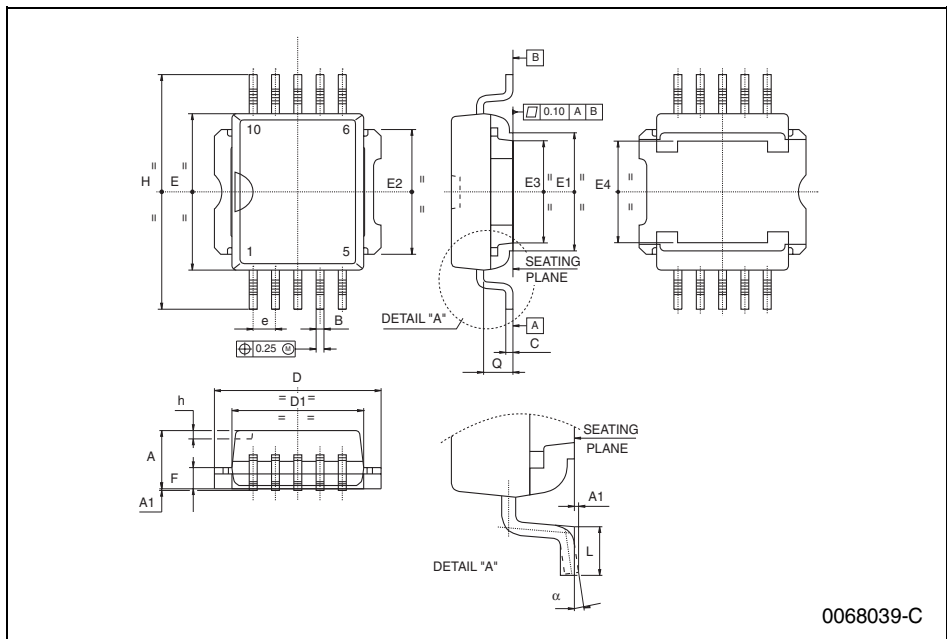


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

**PowerSO-10 MECHANICAL DATA**

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	3.35		3.65	0.132		0.144
A1	0.00		0.10	0.000		0.004
B	0.40		0.60	0.016		0.024
C	0.35		0.55	0.013		0.022
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.300
e		1.27			0.050	
E	9.30		9.50	0.366		0.374
E1	7.20		7.40	0.283		0.291
E2	7.20		7.60	0.283		0.300
E3	6.10		6.35	0.240		0.250
E4	5.90		6.10	0.232		0.240
F	1.25		1.35	0.049		0.053
h		0.50			0.002	
H	13.80		14.40	0.543		0.567
L	1.20		1.80	0.047		0.071
q		1.70			0.067	
$\alpha$	0°		8°			



## 5 Revision history

Table 8. Revision history

Date	Revision	Changes
08-Feb-2007	1	First release
13-Sep-2007	2	New section has been added: <a href="#">2.1: Electrical characteristics (curves)</a>

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